



Active Heat Sink



Passive Heat Sink

FEATURES

- The Intel® Atom™ N270 and 945GSE platform that provides cost effective solution technology
- Intel® Atom™ N270 + 945GSE + ICH7M platform brings under 10W TDP solution for easy fan-less applications
- SATA and IDE interface provide best cost effective functions for market
- Architecture of module and carrier boards speeds up time-to-market of tailor-made equipment
- Support one SODIMM socket and up to 2GB memory size

GENERAL	
Processor	CPU & Package: Intel® Atom™ N270 1.6GHz in FCPGA package FSB: 533MHz
Chipset/Core Logic	Intel® 945GSE and ICH7M
System Memory	Up to 2GB DDR2 533 SDRAM on one SO-DIMM socket
BIOS	Award BIOS
Storage Devices	EIDE: Support one EIDE channel with Ultra DMA 100/66/33 SATA: Support two SATA 150 drives
Solid State Disk	N/A
Watchdog Timer	N/A
Expansion Interface	- One SDVO port - Three PCI Express x1 - Four PCI devices - LPC interface - AC'97/High definition audio interface
Hardware Monitoring	CPU temperature
Dimension	Dimension : 125(L) x 95(W) mm; 4.9"(L) x 3.7" (W)
Environment	Operating Temperature: 0 to 60°C Storage Temperature: -20 to 80°C Relative Humidity: 5% to 90%, non-condensing

ORDERING GUIDE

Standard	PCOM-B214VG Intel® Atom™ processor based Type II COM
	, ,,
	Express module with DDR2 SDRAM, VGA,
	Gigabit Ethernet and USB

I/O	
MIO	N/A
IrDA	N/A
Ethernet	One Gigabit Ethernet Controller (Intel® WG82574L)
Audio	N/A
USB	Eight USB ports
Keyboard & Mouse	N/A

DISPLAY	
Graphic Controller	Intel® 945GSE integrated Graphics Media Accelerator (Intel®GMA 950)
Graphic Memory	Dynamic share system memory up to 224MB (Intel® DVMT 3.0) or static share system memory up to 128MB
Display Interface	- Support CRT, LVDS, TV-out and SDVO display interfaces - CRT display resolution up to 2048x1536@85Hz refresh